Načrtovanje okolja v stavbah - Vgrajeni hladilni in ogrevalni sistemi - 3. del: Načrtovanje in dimenzioniranje (ISO/DIS 11855-3:2020)

Building environment design - Embedded radiant heating and cooling systems - Part 3: Design and dimensioning (ISO/DIS 11855-3:2020)

Umweltgerechte Gebäudeplanung - Flächenintegrierte Strahlheizungs- und -kühlsysteme - Teil 3: Planung und Auslegung (ISO/DIS 11855-3:2020)

Conception de l'environnement des bâtiments - Systèmes intégrés de chauffage et de refroidissement par rayonnement - Partie 3: Conception et dimensionnement (ISO/DIS 11855-3:2020)

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ICS:

91.140.10	Sistemi centralnega ogrevanja	Central heating systems
91.140.30	Prezračevalni in klimatski sistemi	Ventilation and air-conditioning systems

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Building environment design — Embedded radiant heating and cooling systems —

Part 3:
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Foreword

ISO (the International Organization for Standardization) is a worldwide federation of national standards bodies (ISO member bodies). The work of preparing International Standards is normally carried out through ISO technical committees. Each member body interested in a subject for which a technical committee has been established has the right to be represented on that committee. International organizations, governmental and non-governmental, in liaison with ISO, also take part in the work. ISO collaborates closely with the International Electrotechnical Commission (IEC) on all matters of electrotechnical standardization.

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ISO 11855-3 was prepared by Technical Committee ISO/TC 205, *Building environment design*.

ISO 11855 consists of the following parts, under the general title *Building environment design — Design, dimensioning, installation and control of embedded radiant heating and cooling systems*:

— Part 1: *Definition, symbols, and comfort criteria*

— Part 2: *Determination of the design and heating and cooling capacity*

— Part 3: *Design and dimensioning*

— Part 4: *Dimensioning and calculation of the dynamic heating and cooling capacity of Thermo Active Building Systems (TABS)*

— Part 5: *Installation*

— Part 6: *Control*

— Part 7: Input parameters for the energy calculation

Part 1 specifies the comfort criteria which should be considered in designing embedded radiant heating and cooling systems, since the main objective of the radiant heating and cooling system is to satisfy thermal comfort of the occupants. Part 2 provides steady-state calculation methods for determination of the heating and cooling capacity. Part 3 specifies design and dimensioning methods of radiant heating and cooling systems to ensure the heating and cooling capacity. Part 4 provides a dimensioning and calculation method to design Thermo Active Building Systems (TABS) for energy saving purposes, since radiant heating and cooling systems can reduce energy consumption and heat source size by using renewable energy. Part 5 addresses the installation process for the system to operate as intended. Part 6 shows a proper control method of the radiant heating and cooling systems to ensure the maximum performance which was intended in the design stage when the system is actually being operated in a building. Part 7 presents a calculation method for input parameters to ISO 52031.

Introduction

The radiant heating and cooling system consists of heat emitting/absorbing, heat supply, distribution, and control systems. The ISO 11855 series deals with the embedded surface heating and cooling system that directly controls heat exchange within the space. It does not include the system equipment itself, such as heat source, distribution system and controller.

The ISO 11855 series addresses an embedded system that is integrated with the building structure. Therefore, the panel system with open air gap, which is not integrated with the building structure, is not covered by this series.

The ISO 11855 series shall be applied to systems using not only water but also other fluids or electricity as a heating or cooling medium.

The object of the ISO 11855 series is to provide criteria to effectively design embedded systems. To do this, it presents comfort criteria for the space served by embedded systems, heat output calculation, dimensioning, dynamic analysis, installation, control method of embedded systems, and input parameters for the energy calculations.

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Building environment design — Embedded radiant heating and cooling systems —

Part 3:
Design and dimensioning

1 Scope

This part of ISO 11855 establishes a system design and dimensioning method to ensure the heating and cooling capacity of the radiant heating and cooling systems.

The ISO 11855 series is applicable to water based embedded surface heating and cooling systems in residential, commercial and industrial buildings. The methods apply to systems integrated into the wall, floor or ceiling construction without any open air gaps. It does not apply to panel systems with open air gaps which are not integrated into the building structure.

The ISO 11855 series applies also, as appropriate, to the use of fluids other than water as a heating or cooling medium. The ISO 11855 series is not applicable for testing of systems. The methods do not apply to heated or chilled ceiling panels or beams.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

EN 12831, *Heating systems in buildings — Method for calculation of the design heat load*

EN 15243, *Ventilation for buildings — Calculation of room temperatures and of load and energy for buildings with room conditioning systems*

ISO 11855-1, *Building environment design —Embedded radiant heating and cooling systems — Part 1: Definition, symbols, and comfort criteria*

ISO 11855-2, *Building environment design — Embedded radiant heating and cooling systems — Part 2: Determination of the design heating and cooling capacity*

3 Terms and definitions

For the purposes of this document, the terms and definitions given in ISO 11855-1 apply.

4 Symbols and abbreviated terms

For the purposes of this document, the symbols and abbreviations in Table 1 apply.

Table 1 — Symbols and abbreviated terms

Symbol	Unit	Quantity
A_F	m^2	Area of the heating/cooling surface
A_A	m^2	Area of the occupied heating/cooling surface
A_R	m^2	Area of the peripheral heating/cooling surface

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Table 1 *(continued)*

Symbol	Unit	Quantity
c_W	J/(kg·K)	Specific heat of medium
K_H	W/(m²·K)	Equivalent heat transmission coefficient
l_p	m	Distance between the joists
l_W	m	Thickness of the joist
M	kg/s	Design heating/cooling medium flow rate
q_{des}	W/m²	Design heat flux
$q_{des,A}$	W/m²	Design heat flux in the occupied area
$q_{des,R}$	W/m²	Design heat flux in the peripheral area
q_G	W/m²	Limit heat flux
q_{max}	W/m²	Maximum design heat flux
Q_{des}	W	Design heating/cooling capacity
Q_N	W	Design heating/cooling load
$Q_{N,s}$	W	Design sensible cooling load
$Q_{N,l}$	W	Design latent cooling load
Q_{out}	W	Heat output of supplementary heating equipment
R_o	(m² K)/W	Partial inwards heat transmission resistance of the surface structure
R_u	(m² K)/W	Partial outwards heat transmission resistance of the surface structure
$R_{\lambda,B}$	(m²·K)/W	Thermal resistance of surface covering
$R_{\lambda,ins}$	(m²·K)/W	Back side thermal resistance of insulating layer
s_{ins}	m	Effective thickness of thermal insulating layer
W	m	Pipe spacing
h	W/(m² K)	Heat transfer coefficient
λ_{ins}	W/(m·K)	Effective thermal conductivity of the thermal insulation layer
λ_i	W/(mK)	Thermal conductivity of the thermal insulation layer between the joists
λ_w	W/(mK)	Thermal conductivity of the joist
$\theta_{F,max}$	°C	Maximum surface temperature
$\theta_{F,min}$	°C	Minimum surface temperature
θ_i	°C	Design indoor temperature
θ_R	°C	Return temperature of heating/cooling medium
θ_V	°C	Supply temperature of heating/cooling medium
$\theta_{V,des}$	°C	Design supply temperature of heating/cooling medium
$\Delta\theta_H$	K	Heating/cooling medium differential temperature
$\Delta\theta_{H,des}$	K	Design heating/cooling medium differential temperature
$\Delta\theta_{H,G}$	K	Limit of heating/cooling medium differential temperature
$\Delta\theta_{V,des}$	K	Design heating/cooling medium differential supply temperature
σ	K	Temperature drop/rise between supply and return medium

5 Radiant panel

5.1 Floor heating systems

5.1.1 Design procedure

Floor heating system design requires determining heating surface area, type, pipe size, pipe spacing, supply temperature of the heating medium, and design heating medium flow rate. The design steps are as follows:

Step 1: Calculate the design heating load Q_N. The design heating load Q_N shall not include the adjacent heat losses. This step should be conducted in accordance with a standard for heating load calculation, such as EN 12831, based on an index such as operative temperature (OT) (see ISO 11855-1).

Step 2: Determine the area of the heating surface A_F, excluding any area covered by immovable objects or objects fixed to the building structure.

Step 3: Establish a maximum permissible surface temperature in accordance with ISO 11855-1.

Step 4: Determine the design heat flux q_{des} according to Equation (1). For floor heating systems including a peripheral area, the design heat flux of peripheral area $q_{des,R}$ and the design heat flux of occupied area $q_{des,A}$ shall be calculated respectively on the area of the peripheral heating surface A_R and on the area of the occupied heating surface A_A complying with Equation (2).

$$q_{des} = \frac{Q_N}{A_F} \tag{1}$$

$$Q_N = q_{des,R} \cdot A_R + q_{des,A} \cdot A_A \tag{2}$$

Step 5: For the design of the floor heating systems, determine the room used for design with the maximum design heat flux $q_{max} = q_{des}$.

Step 6: Determine the floor heating system such as the pipe spacing and the covering type, and design heating medium differential temperature $\Delta\theta_{H,des}$ based on the maximum design heat flux q_{max} and the maximum surface temperature $\theta_{F,max}$ from the field of characteristic curves according to ISO 11855-2 and 5.1.7 in this part of ISO 11855.

Step 7: If the design heat flux q_{des} cannot be obtained by any pipe spacing for the room used for the design, it is recommended to include a peripheral area and/or to provide supplementary heating equipment. In this case, the maximum design heat flux q_{max} for the embedded system may now occur in another room. The amount of heat output of supplementary heating equipment Q_{out} is determined by the following equation:

$$Q_{out} = Q_N - Q_{des} \tag{3}$$

where design heating capacity Q_{des} is calculated by:

$$Q_{des} = q_{des} \times A_F \tag{4}$$

Step 8: Determine the backside thermal resistance of insulating layer $R_{\lambda,ins}$ and the design heating medium flow rate m (see 5.1.6 and 5.1.8).

Step 9: Estimate the total length of heating circuit.

If intermittent operation is common, the characteristics of the increase of the heat flow and the surface temperature and the time to reach the allowable conditions in rooms just after switching on the system shall be considered.